Meeting the needs of the SMT Age

Table-top Type Reflow Soldering Machine RF-221(Main body)
SH-1(Sub-heater)

This machine is very easy to use. Simply apply cream solder on the board, mount chip parts thereon and place it on the conveyer, so that all chip parts can be reflow soldered in approx. 2min. It is useful for production of small boards with chip parts mounted. Use of the optional top sub-heater allows easy reflow soldering of SOP and CSP, etc.

Features

∗ Being very economically priced, it can be used for small production quantities.
∗ Desk-top type and compact but capable of handling up to 140mm wide board.
∗ Provided with the Teflon belt conveyer, heat efficiency can be enhanced, thus allowing energy saving.
∗ Power consumption is as small as 720W, connectable to ordinary wall sockets.
∗ Use of the sub-heater makes possible reflow soldering of parts with larger heat capacity, such as SOP, CSP, etc., with high efficiency.

Specifications

- Heating section : 2 zones, (W)140×(L)400mm
  Heating method : Hot plate system
  Temperature control : Max. 270°C, P.I.D. temperature controller.
- Conveyor : (W)140mm, Teflon belt. 140 to 1040 mm/min
  Conveyor direction : L → R
  Speed controll : Analog
- Cooling : Natural cooling.
- Power supply : AC100/120V 720W, 50/60 Hz
- External dimensions : (W)800×(D)370×(H)234mm
- Weight : 25kg

Option

SH-1 (Top sub-heater)
- Heater : Quartz tube heater, IR (wavelength: 2 to 10 μm)
- External dimensions : (W)100×(D)330×(H)95mm
- Weight : 1.6kg

Applicable circuit boards

- Dimensions :10mm×10mm to 140mm×150mm
- Board thickness :0.1mm to 2mm
- Height :Max. 20mm
  (At the time of sub-heater use.)

Applications

- Reflow soldering of H-IC and SMT circuit boards.
- Drying of thermosetting adhesives.
- Other heating work.

∗ Specifications subject to change without notice.